Technical Data Sheet

BADAMID® | PPA-HPX GF50 H

(PPA+PA)-GF50

Heat-stabilized and 50% glass fibre reinforced injection moulding grade based on a partially aromatic polyamide

Properties	Test conditions	Test method	Unit	dry as molded	conditioned 23 °C, 50 % r.F.
Mechanical Properties					
Tensile Modulus	23°C, 1 mm/Min	ISO 527-1/2	MPa	18000	17000
Tensile Strength at yield	23°C, 50 mm/Min	ISO 527-1/2	MPa	-	-
Tensile strain at yield	23°C, 50 mm/Min	ISO 527-1/2	%	-	-
Nominal strain at break	23°C, 50 mm/Min	ISO 527-1/2	%	-	-
Tensile stress at break	23°C, 5 mm/Min	ISO 527-1/2	MPa	255	215
Tensile strain at break	23°C, 5 mm/Min	ISO 527-1/2	%	2.5	3.0
Flexural Modulus	23°C	ISO 178	MPa	-	-
Flexural Strength	23°C	ISO 178	MPa	-	-
Charpy Impact Strength	23°C -30°C	ISO 179/1eU ISO 179/1eU	kJ/m² kJ/m²	85 -	100
Charpy Notched Impact Strength	23°C -30°C	ISO 179/1eA ISO 179/1eA	kJ/m² kJ/m²	13 -	15
Izod Notched Impact Strength	23°C -30°C	ISO 180/1A ISO 180/1A	kJ/m² kJ/m²	- -	-
Ball indentation hardness	358 N	ISO 2039-1	MPa	-	-
Thermal Properties					
Melting temperature	10 K/min	ISO 3146	°C	-	
Temperature of deflection under load	0,45 MPa 1,8 MPa 8 MPa	ISO 75-1/2 ISO 75-1/2 ISO 75-1/2	°C °C °C	- 235 190	
Coefficient of linear thermal expansion	parallel across	ISO 11359-2 ISO 11359-2	E-4/K E-4/K	- -	
Thermal conductivity	Test plate 2 mm	DIN 52612-1	W/(m*K)	-	
Maximum service temperature (50% decrease in tensile strength)	some hours 20.000 h	IEC-60216 IEC-60216	°C °C	255 130	
Flammability		UL94 UL94 UL94 UL94	Wall thickness mm Rating Wall thickness mm Rating	0.75 HB 1.5 HB	
Glow wire test GWIT		IEC-60695-2-13 IEC-60695-2-13 IEC-60695-2-13 IEC-60695-2-13	Wall thickness mm Temperature °C Wall thickness mm Temperature °C	- - - -	
Glow wire test GWFI		IEC-60695-2-12 IEC-60695-2-12 IEC-60695-2-12 IEC-60695-2-12	Wall thickness mm Temperature °C Wall thickness mm Temperature °C	- - - -	
Electrical Properties					
Relative Permittivity	1 MHz	IEC-62631-2-1	-	-	-
Dissipation Factor	1 MHz	IEC-62631-2-1	E-4	-	-
Spec. Volume Resistivity	-	IEC-62631-3-1	Ohm*cm	1.0E13	-

HongRong Engineering Plastics Co.,Ltd.
Head Office Tel. +85-2-6957-5415
Research Center Tel.+188 1699 6168

Technical Data Sheet

BADAMID® | PPA-HPX GF50 H

(PPA+PA)-GF50

Heat-stabilized and 50% glass fibre reinforced injection moulding grade based on a partially aromatic polyamide

Properties	Test conditions	Test method	Unit	dry as molded	conditioned 23 ° C, 50 % r.F.
Spec. Surface Resistivity	-	IEC-62631-3-2	Ohm	1.0E14	-
Dielectric Strength	-	IEC-60243-1	kV/mm	-	-
Comparative Tracking Index (CTI)	-	IEC-60112	V	600	-
Other Data					
Water absorption	23°C, Saturation	ISO 62	%	4.3	
Moisture absorption	23°C, 50% r.h.	ISO 62	%	1.4	
Density	23°C	ISO 1183	g/cm³	1.59	
Melt Volume Rate (MVR) 	Value Temperature Test Load	ISO 1133 ISO 1133 ISO 1133	cm³/10min °C kg	- - -	
Viscosity number	0,5% in 96% H2SO4	ISO 307	cm³/g	-	
Processing injection molding					
Melt temperature			°C	280 - 300	
Mold temperature			°C	90 -100	
Guide Value Moisture			%	< 0.05	
Drying temperature			°C	120	
Guide Value Drying time			h	2 - 4	

HongRong Engineering Plastics Co.,Ltd.
Head Office Tel. +85-2-6957-5415
Research Center Tel.+188 1699 6168